



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application for:

**Chung Lam**

Serial No.: 09/336,116

Filed: June 18, 1999

For: **BOARD LEVEL DECAPSULATOR**

Examiner: Ahmed, S.

Art Group: 1746

*RECEIVED  
FEB 04 2002  
TC 170U*

**RESPONSE TO OFFICE ACTION**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action mailed September 20, 2001, the Applicant requests reconsideration based on the following remarks.

**REMARKS**

The Examiner rejects claims 9, 13 and 16 under 35 U.S.C. §102(b) as being anticipated by Wensink (U.S. Patent No. 5,443,675) ("Wensink"). The Examiner states that, "Wensink further discloses that the etch head is removably attached with the integrated circuit or the fixture having IC attached with the connector or circuit board (col. 4, lines 56-64)." (Office Action at paragraph 2)

The Applicant respectfully contends that Wensink does not teach or contemplate decapsulation of an integrated circuit package that is mounted to a printed circuit board as claimed by the Applicant. The Applicant is unable to find at the Examiner's cited reference (col. 4, lines 56-64) any reference to a printed circuit board. The title of the Wensink reference, "Plastic Mold Package Device Decapsulator..." is consistent with the problems and advantages as identified in the summary of the Wensink reference. For example, the field of the invention states "The present invention relates generally to electronic device plastic mold package decapsulation, and more particularly to jet etching of such devices." (Col. 1, lines 7-11)